

HDPE (high density polyethylene) continuous fiber (uni-directional) reinforced thermoplastic composite tape, 70% E-glass by weight

Celstran® CFR-TP HDPE GF70-01 is a 70% E-glass by weight HDPE (high density polyethylene) continuous fiber (unidirectional) reinforced thermoplastic composite tape. The material exhibits a high strength-to-weight ratio, excellent toughness and chemical resistance. It is well suited for industrial, automotive and sporting goods applications where cost and process ability are critical. The material is available in natural and black colors. Alternate tape widths and thicknesses may be available.

Product information

Fiber volume content	46.5 %	ISO 11667
Ply thickness	0.25 mm	ISO 16012
Tape width	305 mm	ISO 16012
Fiber areal weight	308 g/m²	

Typical mechanical properties

Tensile Modulus, tape 0°	35300	MPa	ASTM D 3039 M
Tensile Strength, tape 0°	864	MPa	ASTM D 3039 M
Tensile strain at failure, tape 0°	2.67	%	ASTM D 3039 M
Flexural Modulus	34700	MPa	ASTM D 790
Flexural Strength	465	MPa	ASTM D 790

Thermal properties

Melting temperature, 10 ° C/min	127 °C	ISO 11357-1/-3
Glass transition temperature, 10°C/min	-109 °C	ISO 11357-1/-3
Spec. heat capacity solid	1.18 J/(kg K)	Internal
Thermal conductivity in plane, in flow	0.98 W/(m K)	ASTM E 1461
Thermal conductivity in plane, cross flow	0.72 W/(m K)	ASTM E 1461

Other properties

Density 1710 kg/m³ ISO 1183

Additional information

Compression molding

Celstran® CFR-TP Tape Laminate Processing Guidelines

Celstran® CFR-TP can be molded using a heated platen compression molding press. A hardened steel, aluminum or flexible tooling can be used depending on the application. The tool should be treated with a mold release prior to molding.

The molding cycle consists of the following steps:

- 1. The platens should be heated above the polymer matrix melt temperature.
- 2. The individual lamina should be constructed and placed in the tool to achieve the desired laminate reinforcement orientation.
- 3. The tool is placed between the platens and the platens are closed to achieve a contact pressure on the tool less than 30 psi (2 bar).







- 4. The tool is allowed to rise in temperature until stabilizing at the initial temperature the platens were set to.
- 5. The pressure is increased to the desired amount and held for a recommended time.
- 6. Air and/or water cooling is initiated until the material reaches a temperature sufficiently below the melt and peak crystallization temperatures wherein the pressure is reduced to a contact pressure less than 15 psi (1 bar).
- 7. The tool is continually cooled until reaching a temperature, typically at or below the glass transition point, at which the pressure is completely removed and the part de-molded from the tool. It should be noted that the choice of tooling, geometry and heating/cooling mechanisms will greatly dictate processing conditions, and thus, optimization specific to the individual molders' capabilities is necessary. Additionally, the resin is what dictates the molding temperatures, whereas the sample thickness is what determines the time. As the thickness increases, the time at melt should also increase to account for the time for heat to conduct to the center of the laminate.

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Resin: HDPE

Drying Time: It is normally not necessary to dry HDPE

Drying Temperature: It is normally not necessary to dry HDPE

Platen Temperature: 390°F, 199°C Press Pressure: 28 psi, 1.9 bar

Time at Melt: 2 min

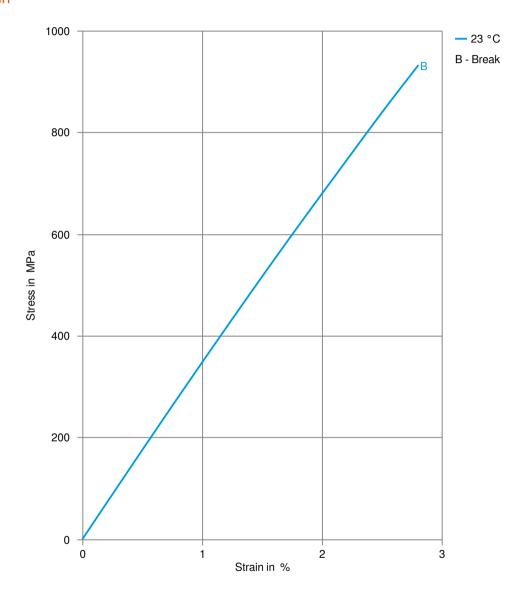
Cooling Rate: 15-30°F/min, 8-17°C/min Material Removal Temperature: 150°F, 66°C







Stress-strain

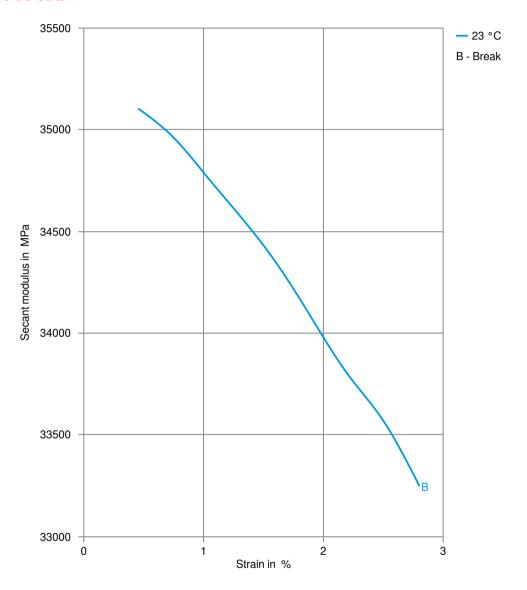








Secant modulus-strain



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